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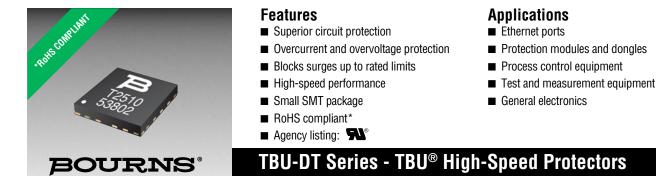
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General Information

The TBU-DT Series of Bourns® TBU® (Transient Blocking Unit) products are very low capacitance dual unidirectional high-speed surge protection components designed to protect against faults caused by short circuits, AC power cross, induction and lightning surges.

The TBU-DT series is a unidirectional TBU[®] device; the TBU[®] protector will trip in less than 1 µs when the current reaches the maximum value in one direction only, that is when Pin 1 is positive in voltage with respect to Pin 2, and Pin 4 is positive with respect to Pin 3. No current limiting exists in the opposite polarity, and the TBU® device appears as resistive in nature. The reverse current should not exceed the maximum trigger current level of the TBU® device. An external diode may be used to prevent reverse current in DC biased applications.

The TBU® protector blocks surges and provides an effective barrier behind which sensitive electronics will not be exposed to large voltages or currents during surge events. After the surge, the TBU® device resets when the voltage across the TBU® device falls to the V_{reset} level. The TBU® device will automatically reset on lines which have no DC bias or have DC bias below Vreset (such as unpowered signal lines).

The TBU® device is provided in a surface mount DFN package and meets industry standard requirements such as RoHS and Pb Free solder reflow profiles.

Absolute Maximum Ratings (@ T_A = 25 °C Unless Otherwise Noted)

Line Side Load Side Line Side Load Side 3 TBU[®] Device

Agency Listing

Description						
UL	File Number: E315805					

Symbol	Parameter	Part Number	Value	Unit	
V _{imp}	Deals impulse voltage withstand with duration loss than 10 ms	TBU-DT065-xxx-WH	650	V	
	Peak impulse voltage withstand with duration less than 10 ms	TBU-DT085-xxx-WH	850	v	
V _{rms}	Continuous A.C. BMS voltage	TBU-DT065-xxx-WH	300	V	
	Continuous A.C. RMS voltage	TBU-DT085-xxx-WH	425	v	
T _{op}	Operating temperature range		-40 to +125	°C	
Tstg	Storage temperature range		-65 to +150	°C	

Electrical Characteristics (@ T_A = 25 °C Unless Otherwise Noted)

Symbol	Parameter	Parameter Part Number					Unit	
			TBU-DTxxx-100-WH	100	150	200		
I _{trigger}	Current required for th	e device to go from operating state to	TBU-DTxxx-200-WH	200	300	400	mA	
	protected state		TBU-DTxxx-300-WH	300	450	600		
	-		TBU-DTxxx-500-WH	500	750	1000		
		$V_{\rm max} = 650 V I_{\rm max} (min) = 100 mA$	TBU-DT065-100-WH		8.5	10.0		
		$V_{imp} = 650 V$ $I_{trigger}$ (min.) = 200 mA	TBU-DT065-200-WH		5.6	6.6		
		$ \begin{array}{ c c c c } V_{imp} = 650 \ V & I_{trigger} \ (min.) = \ 100 \ mA \\ V_{imp} = 650 \ V & I_{trigger} \ (min.) = \ 200 \ mA \\ V_{imp} = 650 \ V & I_{trigger} \ (min.) = \ 300 \ mA \\ V_{imp} = 650 \ V & I_{trigger} \ (min.) = \ 500 \ mA \\ \end{array} $	TBU-DT065-300-WH		4.6	5.6		
		$V_{imp} = 650 \text{ V}$ $I_{trigger} (min.) = 500 \text{ mA}$	TBU-DT065-500-WH		4.0	4.8		
R _{device}	Series resistance of the TBU® device					1.0	Ω	
		$V_{imp} = 850 \text{ V}$ Itrigger (min.) = 100 mA	TBU-DT085-100-WH		10.3	12.1		
		$V_{imp} = 850 \text{ V}$ Itrigger (min.) = 200 mA	TBU-DT085-200-WH		7.4	8.7		
		$V_{imp} = 850 \text{ V}$ Itrigger (min.) = 300 mA	TBU-DT085-300-WH		6.5	7.7		
		$ \begin{array}{ c c c c c } V_{imp} = 850 \ V & I_{trigger} \ (min.) = \ 100 \ mA \\ V_{imp} = 850 \ V & I_{trigger} \ (min.) = \ 200 \ mA \\ V_{imp} = 850 \ V & I_{trigger} \ (min.) = \ 300 \ mA \\ V_{imp} = 850 \ V & I_{trigger} \ (min.) = \ 500 \ mA \end{array} $	TBU-DT085-500-WH		5.8	6.9		
R _{match}	Package resistance m	atching of the TBU [®] device #1 - TBU [®] de	-0.5		+0.5	Ω		
t _{block}	Time for the device to	device to go from normal operating state to protected state				1	μs	
lQ	Current through the tr	iggered TBU [®] device with 50 Vdc circuit v	0.25	0.50	1.00	mA		
V _{reset}	Voltage below which t	he triggered TBU® device will transition to	10	14	18	V		
R _{th(j-l)}	Junction to package p	ads - FR4 using recommended pad layou	İ	116		°C/W		
R _{th(j-l)}	Junction to package p	ads - FR4 using heat sink on board (6 cm	1 ²)		96		°C/W	

*RoHS Directive 2002/95/EC Jan. 27, 2003 including annex and RoHS Recast 2011/65/EU June 8, 2011. Specifications are subject to change without notice.

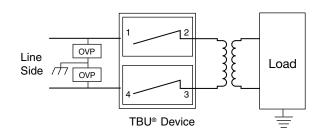
The device characteristics and parameters in this data sheet can and do vary in different applications and actual device performance may vary over time.

Users should verify actual device performance in their specific applications.

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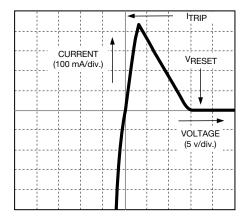
Reference Application

The TBU[®] device can be used to protect against excessive voltage surges in transformer coupled equipment, as shown in the figure below. The TBU[®] protector prevents any surges from causing damage. An overvoltage protection device, such as an MOV or GDT, may be used to provide additional overvoltage protection if the surge voltage is likely to be above the maximum rating of the TBU[®] device.



Performance Graphs

V-I Characteristic - TBU-DT085-300-WH (Pin 2-1 & Pin 3-4)



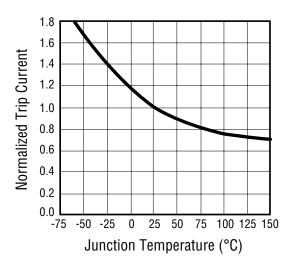
Basic TBU Operation

The TBU[®] device is a silicon-based, solid-state, resettable device which is placed in series with a signal path. The TBU[®] device operates in approximately 1 μ s - once line current exceeds the TBU[®] device's trigger current I_{trigger}. When operated, the TBU[®] device will limit the current to less than the I_{trigger} value within the t_{block} duration. If voltage above V_{reset} is continuously sustained, the TBU[®] device will subsequently reduce the current to a quiescent current level within a period of time that is dependent upon the applied voltage.

After the surge, the TBU[®] device resets when the voltage across the TBU[®] device falls to the V_{reset} level. The TBU[®] device will automatically reset on lines which have no DC bias or have DC bias below V_{reset} (such as unpowered signal lines).

If the line has a normal DC bias above V_{reset} , the voltage across the TBU[®] device may not fall below V_{reset} after the surge. In such cases, special care needs to be taken to ensure that the TBU[®] device will reset, otherwise an automatic or manual power down will be required. Bourns application engineers can provide further assistance.

Typical Trigger Current vs. Temperature

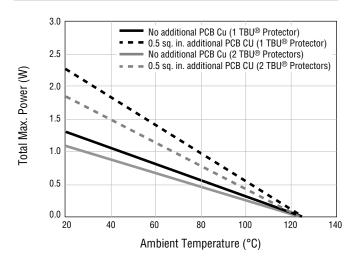


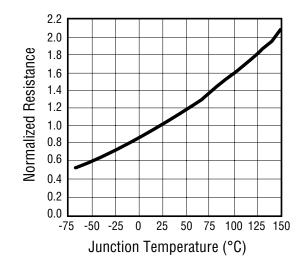
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Performance Graphs (Continued)

Power Derating Curve

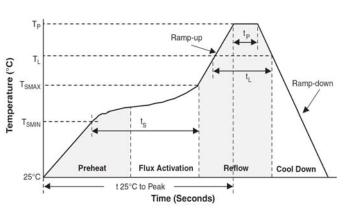




Typical Resistance vs. Temperature

Reflow Profile

Profile Feature	Pb-Free Assembly			
Average Ramp-Up Rate (Tsmax to Tp)	3 °C/sec. max.			
Preheat - Temperature Min. (Tsmin) - Temperature Max. (Tsmax) - Time (tsmin to tsmax)	150 °C 200 °C 60-180 sec.			
Time maintained above: - Temperature (TL) - Time (tL)	217 °C 60-150 sec.			
Peak/Classification Temperature (Tp)	260 °C			
Time within 5 °C of Actual Peak Temp. (tp)	20-40 sec.			
Ramp-Down Rate	6 °C/sec. max.			
Time 25 °C to Peak Temperature	8 min. max.			

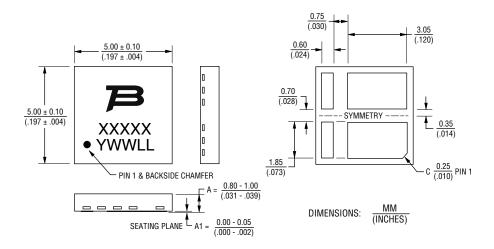


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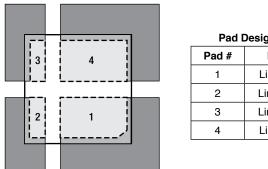
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Product Dimensions



Recommended Pad Layout

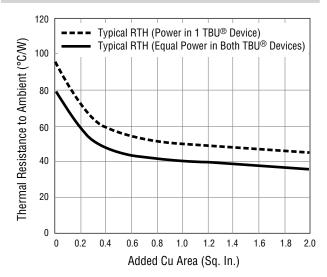
TBU® High-Speed Protectors have a 100 % matte-tin termination finish. For improved thermal dissipation, the recommended layout uses PCB copper areas which extend beyond the exposed solder pad. The exposed solder pads should be defined by a solder mask which matches the pad layout of the TBU® device in size and spacing. It is recommended that they should be the same dimension as the TBU® pads but if smaller solder pads are used, they should be centered on the TBU® package terminal pads and not more than 0.10-0.12 mm (0.004-0.005 in.) smaller in overall width or length. Solder pad areas should not be larger than the TBU® pad sizes to ensure adequate clearance is maintained. The recommended



Pad Designation						
Pad #	Pin Out					
1	Line Side 1					
2	Line Load 1					
3	Line Load 2					
4	Line Side 2					

Dark grey areas show added PCB copper area for better thermal resistance.

stencil thickness is 0.10-0.12 mm (0.004-0.005 in.) with a stencil opening size 0.025 mm (0.0010 in.) less than the solder pad size. Extended copper areas beyond the solder pad significantly improve the junction to ambient thermal resistance, resulting in operation at lower junction temperatures with a corresponding benefit of reliability. All pads should soldered to the PCB, including pads marked as NC or NU but no electrical connection should be made to these pads. For minimum parasitic capacitance, it is recommended that signal, ground or power signals are not routed beneath any pad.

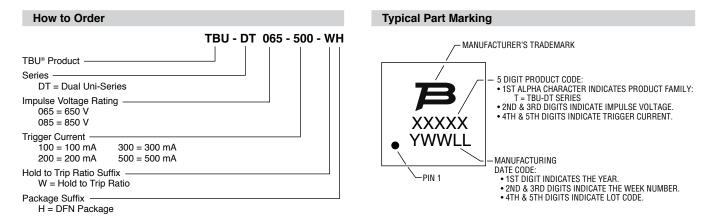


Thermal Resistance vs. Additional PCB Cu Area

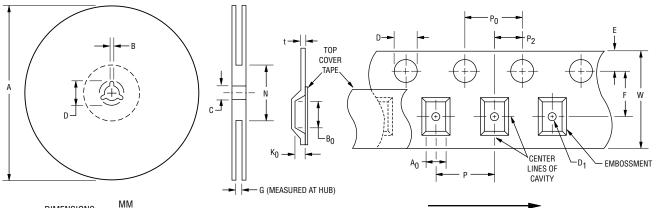
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Packaging Specifications



DIMENSIONS: (INCHES)

Max.

330

(13.002)

Α

Min

326

(12.835)

QUANTITY: 3000 PIECES PER REEL

Min

12.8

(.504)

С

Max.

13.5

(.531)

USER DIRECTION OF FEED

-

D

Min.

20.2

(.795)

G Ν Max Ref. Ref. 16.5 102 (.650) (4.016)

A0		B0		D		D1		E		F	
Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	Min.	max.
<u>5.15</u> (.203)	<u>5.35</u> (.211)	<u>5.15</u> (.203)	<u>5.35</u> (.211)	<u>1.5</u> (.059)	$\frac{1.6}{(.063)}$	<u>1.5</u> (.059)	-	<u>1.65</u> (.065)	<u>1.85</u> (.073)	<u>5.45</u> (.214)	<u>5.55</u> (.218)
K0		Р		P0		P2		t		W	
Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.
<u>1.0</u> (.039)	<u>1.2</u> (.047)	<u>7.9</u> (.311)	<u>8.1</u> (.319)	<u>3.8</u> (.150)	<u>4.2</u> (.165)	<u>1.95</u> (.077)	<u>2.05</u> (.081)	<u>0.25</u> (.010)	<u>0.35</u> (.014)	<u>11.7</u> (.461)	<u>12.3</u> (.484)

В

Max.

2.5

(.098)

Min.

1.5

(.059)

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